In the Claims

Please amend claims 13-15, 17-18, 35-42, and 44-47 as follows below.

Please add new claims 50-55 as follows below.

Please accept a marked up version of the entire set of pending claims including the amendments made herein.

Marked Up Version of Pending Claims

1-12. (Cancelled)

13. (Currently Amended) A method for assembling an electronic package, comprising:

forming a housing which has a bond pad located on a ~~first~~ top surface of a bond shelf, the bond shelf having ~~a second~~ an inner side surface along a thickness of the bond shelf;

forming a conductive strip lengthwise along the inner side ~~second~~ surface of the bond shelf; and

removing a portion of the conductive strip along the ~~second~~ inner side surface of the bond shelf to form a pair of separate conductive strips lengthwise along the ~~second~~ inner side surface of the bond shelf.

14. (Currently Amended) The method as recited in claim 13, wherein

the conductive strip is formed by plating a conductive material onto the ~~second~~ inner side surface of the bond shelf.

15. (Currently Amended) The method as recited in claim 13, wherein

the portion of the conductive strip is removed by drilling a portion of the ~~second~~ inner side surface of the bond shelf including the conductive strip.

16. (Previously Presented) The method as recited in claim 13, further comprising:

mounting an integrated circuit to the housing and connecting the integrated circuit to the bond pad.

17. (Currently Amended) The method as recited in claim 14, wherein

the portion of the conductive strip is removed by etching away a portion of the conductive material on the ~~second~~ inner side surface of the bond shelf.

18. (Currently Amended) The method as recited in claim 13, wherein

the conductive strip is formed along the second surface of the bond shelf by

masking ~~all~~ surfaces of the bond shelf except for portions of the bond shelf to be plated, the ~~second~~ inner side surface of the bond shelf being unmasked, and

plating a conductive material onto the ~~second~~ inner side surface of the bond shelf.

19. (Previously Presented) The method as recited in claim 18, wherein

the conductive material is copper, and

the conductive strip is further formed by plating gold onto the copper.

20. (Previously Presented) The method as recited in claim 19, wherein

the portion of the conductive strip is removed by

drilling a portion of the bond shelf.

21-34. (Cancelled)

35. (Withdrawn - Currently Amended) The method as recited in claim 13, wherein

the forming of the conductive strip further includes

forming a portion of the conductive strip around onto the ~~first~~ top surface of the bond shelf to couple to the

bond pad on the ~~first~~ top surface of the bond shelf.

36. (Withdrawn - Currently Amended) The method as recited in claim 35, wherein

the portion of the conductive strip around on the ~~first~~ top surface of the bond shelf to further anchor the conductive strip to the housing.

37. (Withdrawn - Currently Amended) The method as recited in claim 13, wherein

the forming of the conductive strip further includes forming a portion of the conductive strip around onto the ~~first~~ top surface of the bond shelf to form another bond pad on the ~~first~~ top surface of the bond shelf.

38. (Withdrawn - Currently Amended) The method as recited in claim 37, wherein

the portion of the conductive strip around on the ~~first~~ top surface of the bond shelf to further anchor the conductive strip to the housing.

39. (Currently Amended) A method for assembling an electronic package, comprising:

forming a housing which has a bond pad located on a top surface of a bond shelf, the bond shelf having an inside ~~a side~~ surface along an edge of the bond shelf;

plating a conductive material along the inside ~~side~~ surface of the bond shelf; and

removing a portion of the conductive material along the inside ~~side~~ surface of the bond shelf to form a pair of separate conductive strips along the inside ~~side~~ surface of the bond shelf.

40. (Currently Amended) The method of claim 39, wherein the portion of the conductive material is removed by drilling into the edge of the bond shelf including the conductive material and the inside ~~side~~ surface.

41. (Currently Amended) The method of claim 39, wherein the portion of the conductive material is removed by etching away a portion of the conductive material from the inside ~~side~~ surface of the bond shelf.

42. (Currently Amended) The method of claim 39, wherein, the plating of the conductive material onto the inside ~~side~~ surface of the bond shelf includes masking surfaces of the housing that are not to be

plated and

leaving surfaces of the housing unmasked that are to be plated, including the inside ~~side~~ surface of the bond shelf that is to be plated.

43. (Previously Presented) The method of claim 42, wherein the plating of the conductive material further includes

plating copper onto the unmasked surfaces of the housing, and

plating gold onto the copper.

44. (Currently Amended) The method of claim ~~39~~ 43, wherein the portion of the conductive material is removed by

drilling into the edge of the bond shelf including the conductive material and the inside ~~side~~ surface.

45. (Withdrawn - Currently Amended) The method of claim 39, wherein

the plating of the conductive material further includes

plating a portion of the conductive material from the inside ~~side~~ surface around onto the top surface of the bond shelf to couple to the bond pad on the top surface of the bond shelf.

46. (Withdrawn - Currently Amended) The method of claim 45, wherein

the portion of the conductive material plated around onto the inside ~~side~~ surface of the bond shelf to further anchor the conductive material to the housing.

47. (Withdrawn - Currently Amended) The method of claim 39, wherein

the plating of the conductive material further includes plating a portion of the conductive material from the inside ~~side~~ surface around onto the top surface of the bond shelf to form another bond pad on the top surface of the bond shelf.

48. (Withdrawn) The method of claim 47, wherein

the portion of the conductive material plated around onto the top surface of the bond shelf to further anchor the conductive material to the housing.

49. (Withdrawn) The method of claim 39, further comprising:

mounting an integrated circuit to the housing and connecting the integrated circuit to the bond pad.

50. (New) A method for assembling an electronic package, comprising:

forming a housing which has a plurality of bond pads located on a top surface of a bond shelf, the bond shelf forming a rectangular cavity wall along an inner side of the bond shelf;

forming a conductive strip lengthwise along the rectangular cavity wall of the bond shelf; and

removing portions of the conductive strip along the rectangular cavity wall of the bond shelf to form a plurality of separate conductive strips along the rectangular cavity wall of the bond shelf.

51. (New) The method as recited in claim 50, wherein the conductive strip is formed by plating a conductive material onto the rectangular cavity wall of the bond shelf.

52. (New) The method as recited in claim 50, wherein portions of the conductive strip are removed by drilling a portion of the rectangular cavity wall of the bond shelf including the conductive strip.

53. (New) The method as recited in claim 50, further comprising:

mounting an integrated circuit to the housing and connecting the integrated circuit to at least one of the plurality of bond pads.

54. (New) The method as recited in claim 50, wherein portions of the conductive strip are removed by

etching away portions of the conductive material on the rectangular cavity wall of the bond shelf.

55. (New) The method as recited in claim 50, wherein the conductive strip is formed along the rectangular cavity wall of the bond shelf by

masking surfaces of the bond shelf except for portions of the bond shelf to be plated, the rectangular cavity wall of the bond shelf being unmasked, and

plating a conductive material onto the rectangular cavity wall of the bond shelf.

REMARKS

This is in response to the Notice of Non-Compliant Amendment mailed on 08/26/2003.

In the Notice of Non-Compliant Amendment, it was noted that a complete listing of all the claims was not presented in the preliminary amendment filed on 08/11/2003. In particular, a portion of withdrawn claim 48 was not presented and withdrawn claim 49 in its entirety was not presented due to an inadvertent error.

In response, Applicant respectfully resubmits herein the entire "Amendments to the claims" section of the prior document with a complete listing of all claims 1-55 in ascending numerical order including claims 48-49 in their entirety.

Respectfully submitted,
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Dated: September 5, 2003

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